

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently amended): Chemical mechanical polishing (CMP) equipment for use in planarizing a semiconductor wafer, said equipment comprising : a turntable, a polishing pad disposed atop said turntable; a slurry supply unit that dispenses slurry onto an upper surface of the polishing pad; a head polishing unit having a polishing head positionable over the upper surface of the polishing pad, said polishing head being rotatable to rotate a wafer atop said polishing pad; a conditioning unit having a pad conditioning head that is movable into contact with said polishing pad and has a serrated surface that conditions said polishing pad when in contact with the pad; and a cleaning solution supply unit through which a cleaning solution is supplied, said cleaning solution supply unit ~~having at least one~~ including at least one cleaning solution supply line disposed beside said turntable, and a spray nozzle disposed at an end of each said cleaning solution supply line and oriented to spray the cleaning solution over a region encompassing ~~at least a portion of the entire~~ upper surface of said polishing pad, and said polishing head and said conditioning head.

Claim 2 (Currently amended): The CMP equipment of claim 1, wherein said cleaning solution supply unit further includes ~~a cleaning solution supply line, said~~

~~spray nozzle being disposed at an end of the cleaning solution supply line, and a flow~~
regulator disposed in-line with each said cleaning solution supply line so as to control
the pressure of the cleaning solution flowing from each said spray nozzle.

Claims 3 – 5 (Canceled)